



## STCCP27A

1.8V/2.8V High speed dual differential line receivers,  
Compact camera port decoder, I<sup>2</sup>C control line

### Feature summary

- SUB-Low voltage differential signaling inputs:  
 $V_{ID} = 100\text{mV}$  with  $R_T = 100\Omega$ ,  $C_L = 10\text{pF}$
- High signaling rate:  
 $f_{IN} = 416\text{MHz max}$  (D+, D-, CLK+, CLK-)  
 $f_{OUT} = 52\text{MHz max}$  (D1-D8, CLK)
- Very high speed:  
 $t_{pLH} - t_{pHL} = 3.5\text{ns}$  (typ) at  $V_{DD} = 2.8\text{V}$ ;  $V_L = 1.8\text{V}$
- Operating voltage range:  
 $V_{DD}(\text{OPR}) = 2.65\text{V to } 3.6\text{V}$   
 $V_L(\text{OPR}) = 1.65\text{V to } 1.95\text{V}$
- Symmetrical output impedance  
(D1-D8, H-SYNC, V-SYNC, CLK):  
 $I_{OH} = I_{OL} = 8\text{mA}$  (min) at  $V_{DD} = 2.65\text{V}$ ;  $V_L = 1.8\text{V}$
- Low power dissipation  
(Disabled: EN=Gnd):  
 $I_{SOFF} = I_{DD} + I_L = 10\mu\text{A}$  (max)
- CMOS logic input threshold  
(EN, SYNC\_SEL):  
 $V_{IL} = 0.3 \times V_{DD}$ ;  $V_{DD} = 2.65\text{V to } 3.6\text{V}$   
 $V_{IH} = 0.7 \times V_{DD}$ ;  $V_{DD} = 2.65\text{V to } 3.6\text{V}$
- Bidirectional level translator line  
(I/OV<sub>DD</sub>, I/OV<sub>L</sub>) for I<sup>2</sup>C communications:  
400kHz max frequency  
 $I_{OH} = 20\mu\text{A}$  (min.) at  $V_{DD} = 2.8\text{V}$ ;  $V_L = 1.8\text{V}$   
 $I_{OL} = 1\text{mA}$  (min.) at  $V_{DD} = 2.8\text{V}$ ;  $V_L = 1.8\text{V}$
- 3.6V Tolerant on inputs (EN, SYNC\_SEL)
- Leadfree  $\mu\text{TFBGA}$  package  
(RoHS restriction of hazardous substances)



### Description

The STCCP27A receiver converts the subLVDS clock/datastream (up to 416 Mbps throughput bandwidth) back into parallel 8 bits of CMOS/LVTTL. The device recognizes the CCP 32bit start of frame (SOF), end of frame (EOF), start of line (SOL) and end of line (EOL) sequences to generate the H-SYNC and V-SYNC signals. Output LVTTL clock (up to 52 MHz) is transmitted in parallel with data. Input and Output data are rising edge strobe. This chipset is an ideal means to link mobile camera modules to baseband processors. In order to minimize static current consumption, it is possible to shut down the device when the interface is not being used by a power-down (EN) pin that reduces to 10 $\mu\text{A}$  the Maximum Current Consumption making this device ideal for portable applications like Mobile Phone, Portable Battery Equipment. Two dedicated I<sup>2</sup>C lines are provided to translate bidirectional controls from camera and  $\mu\text{C}$  devices. The STCCP27A is offered in a  $\mu\text{TFBGA}$  package to optimize PCB space. All inputs and outputs are equipped with protection circuits against static discharge, giving them ESD immunity from transient excess voltage. The STCCP27A is characterized for operation over the commercial temperature range -40°C to 85°C.

### Order code

Part number	Temperature Range	Package	Comments
STCCP27ATBR	-40 to 85 °C	$\mu\text{TFBGA25}$ 3x3mm (Tape & Reel)	3000 parts per reel

---

## Contents

<b>1</b>	<b>Schematic diagram</b> .....	<b>3</b>
<b>2</b>	<b>Pin configuration</b> .....	<b>5</b>
<b>3</b>	<b>Maximum ratings</b> .....	<b>7</b>
<b>4</b>	<b>Electrical characteristics</b> .....	<b>8</b>
<b>5</b>	<b>Timing diagram</b> .....	<b>10</b>
<b>6</b>	<b>Package mechanical data</b> .....	<b>15</b>
<b>7</b>	<b>Revision history</b> .....	<b>18</b>

# 1 Schematic diagram

Figure 1. Simplified application block diagram

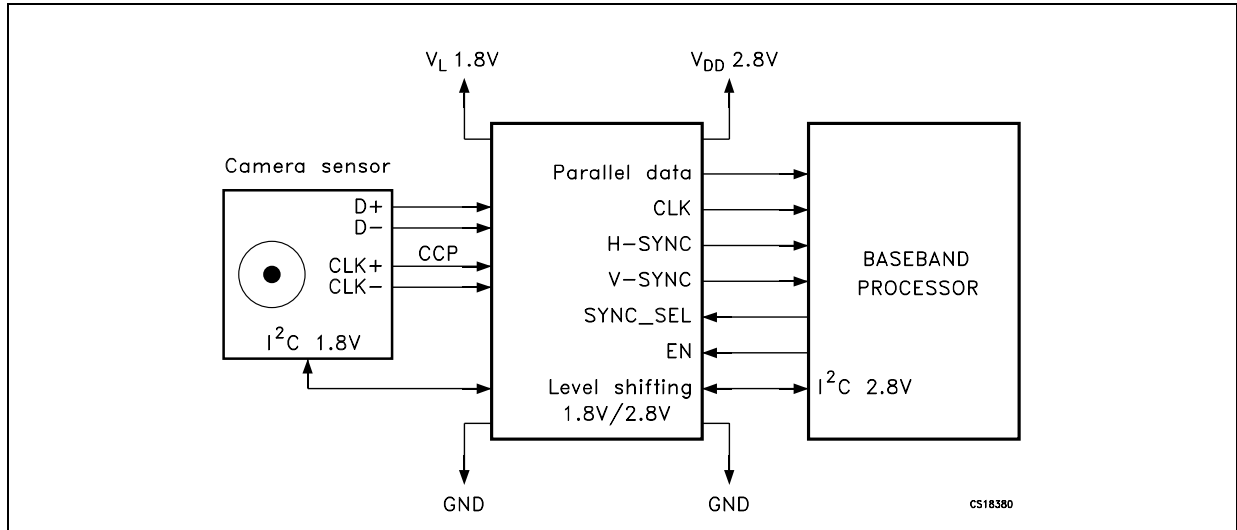


Figure 2. Block diagram

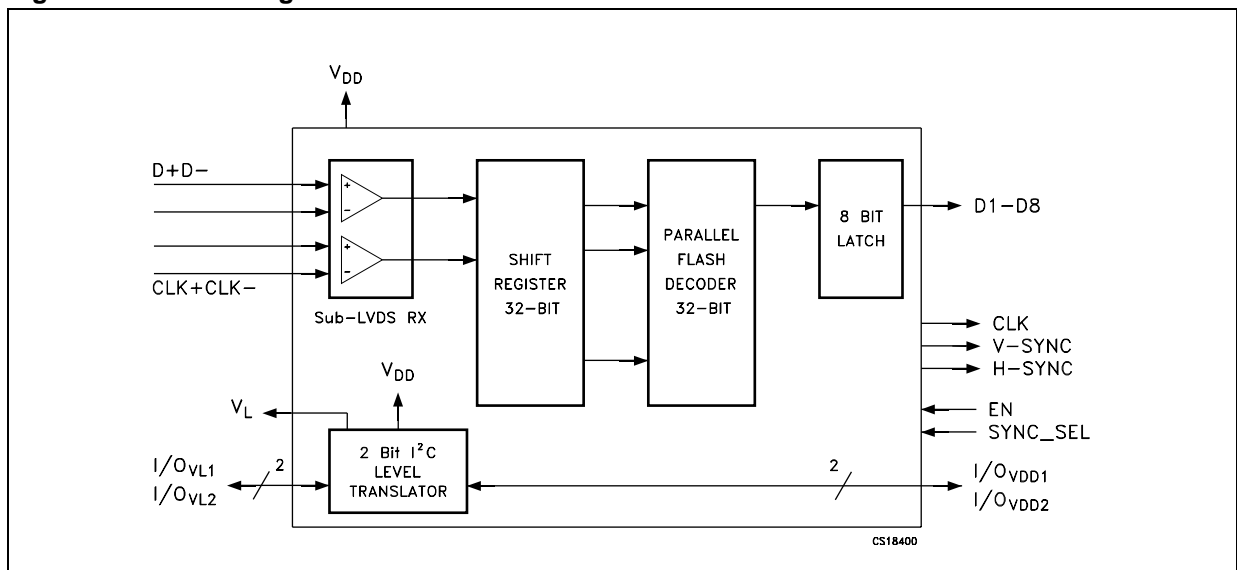
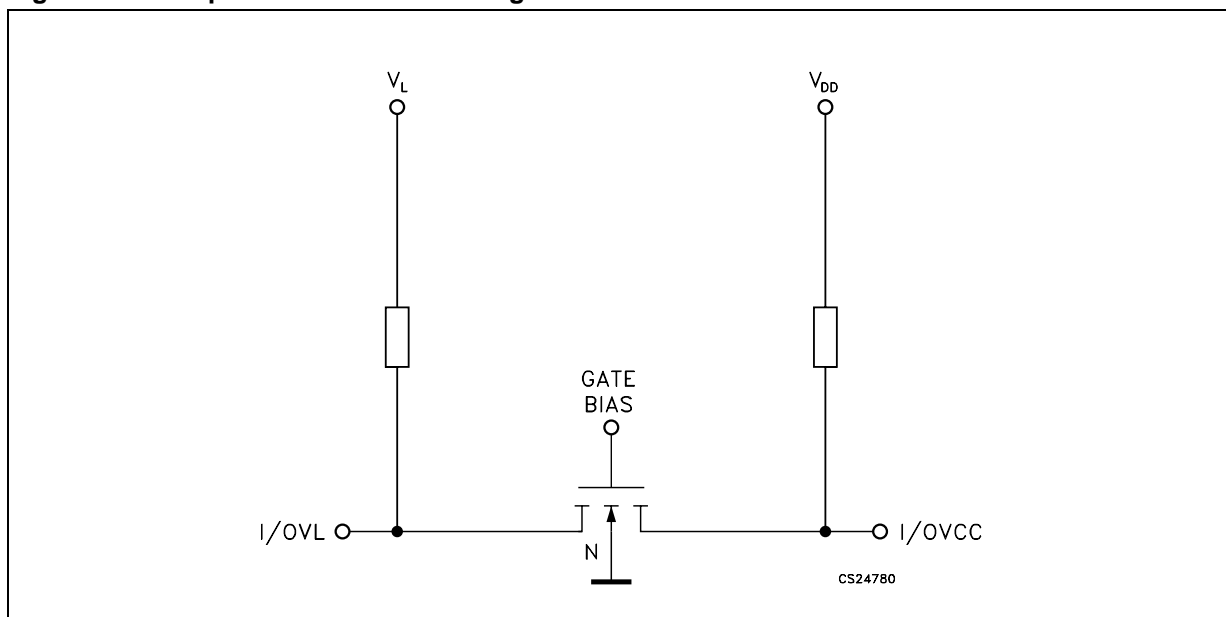


Figure 3. Simplified I<sup>2</sup>C line block diagram



## 2 Pin configuration

Figure 4. Pin configuration (top through view - bumps are on the other side)

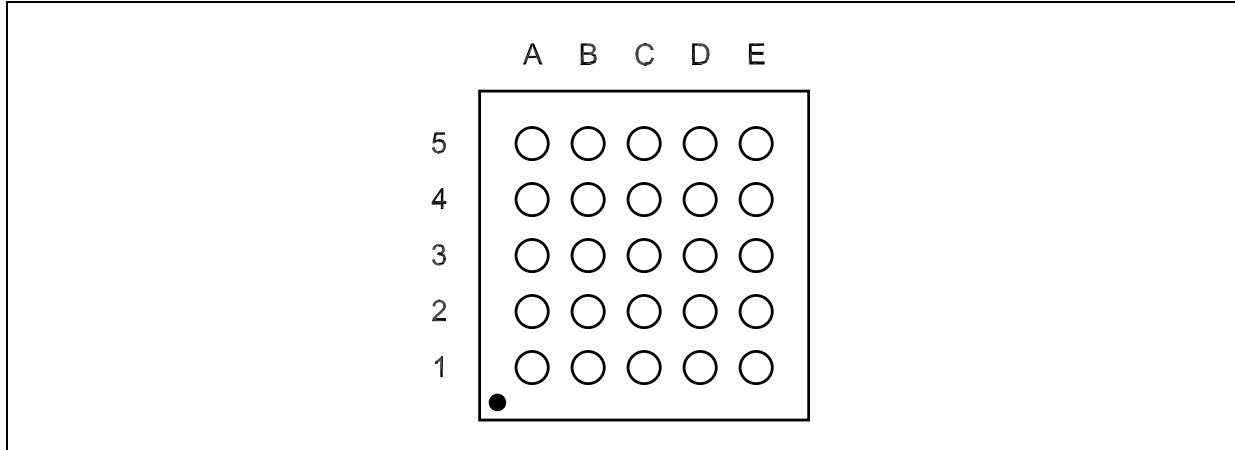


Table 1. Pin description

Pin n°	Symbol	Name and function
D5	D1	Decoder Output (LSB)
E5	D2	Decoder Output
D4	D3	Decoder Output
E4	D4	Decoder Output
D2	D5	Decoder Output
E2	D6	Decoder Output
D1	D7	Decoder Output
E1	D8	Decoder Output (MSB)
A2, A1	D+, D-	Differential Data Receiver Inputs
A5, A4	CLK+, CLK-	Differential CLK Receiver Inputs
B3	EN	Receivers Enable Input
D3	CLK	Clock Output
C3	H-SYNC	Horizontal Sync Output
B2	V-SYNC	Vertical Sync Output
A3, E3	GND	Ground
C5	V <sub>DD</sub>	Main Supply Voltage
B4	SYNC SEL	Select Sync Input
C1	V <sub>L</sub>	Secondary Supply Voltage
B1, C2	I/O <sub>VL1</sub> , I/O <sub>VL2</sub>	I <sup>2</sup> C Line (V <sub>L</sub> Referred)
B5, C4	I/O <sub>VDD1</sub> , I/O <sub>VDD2</sub>	I <sup>2</sup> C Line (V <sub>DD</sub> Referred)

Table 2. Main function table

Input						Output				Function
Enable	SYNC_SEL	D+	D-	CLK+	CLK-	V-SYNC	H-SYNC	D1-D8	CLK	
L	X	X	X	X	X	L	L	L	L	CCP disabled
H	H	SOF (FF <sub>H</sub> 00 <sub>H</sub> 00 <sub>H</sub> 02 <sub>H</sub> )				H	H	See detailed timing diagram		Start of frame
H	H	EOF (FF <sub>H</sub> 00 <sub>H</sub> 00 <sub>H</sub> 03 <sub>H</sub> )				L	L			End of frame
H	H	SOL (FF <sub>H</sub> 00 <sub>H</sub> 00 <sub>H</sub> 00 <sub>H</sub> )				No change	H			Start of line
H	H	EOL (FF <sub>H</sub> 00 <sub>H</sub> 00 <sub>H</sub> 01 <sub>H</sub> )				No change	L			End of line
H	L	X	X	X	X	L	L	D+, D-	See detailed timing diagram	Disabled sync (D1-D8 will get out data, including sync code)

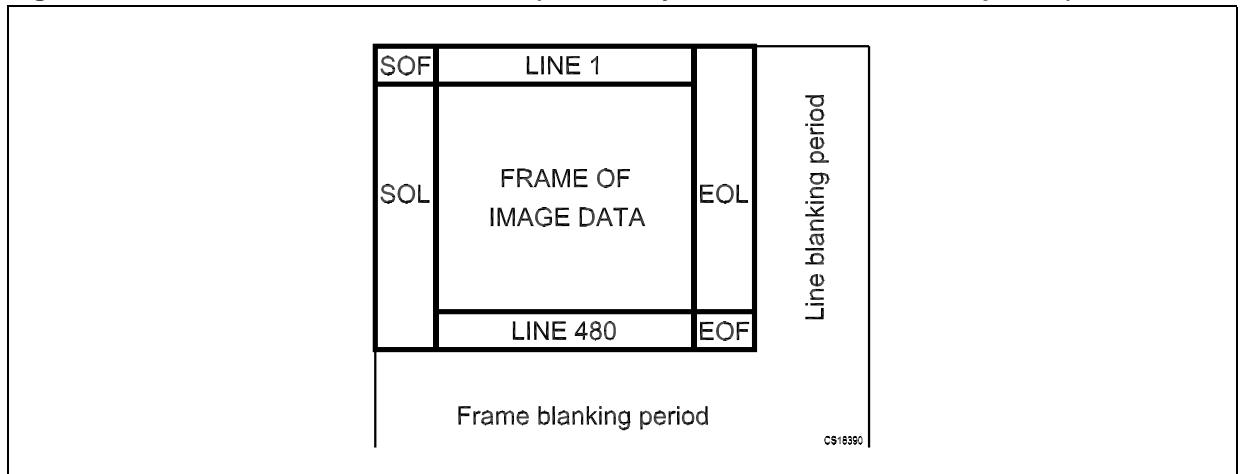
Z = High Impedance, L = Low Voltage Level, H = High Voltage Level, X = Don't care

Table 3. I<sup>2</sup>C Bus function table

Enable	I/O Input		Function
	I/O <sub>VDD</sub>	I/O <sub>VL</sub>	
X	L	L	I <sup>2</sup> C Comm.
X	V <sub>DD</sub>	V <sub>L</sub>	I <sup>2</sup> C Comm.
X	Open	V <sub>L</sub>	I <sup>2</sup> C Comm.
X	V <sub>DD</sub>	Open	I <sup>2</sup> C Comm.

Open: If I/O<sub>VDD</sub> is not driven then the I/O<sub>VL</sub> will go in high level V<sub>L</sub> by embedded 10kΩ pull-up resistor; If I/O<sub>VL</sub> is not driven then the I/O<sub>VCC</sub> will go in high level V<sub>DD</sub> by embedded 10KΩ pull-up resistor

Figure 5. Frame structure In VGA case (allowed synchronization codes sequence)



### 3 Maximum ratings

**Table 4. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DD}$	Main supply voltage	-0.5 to 4.6	V
$V_L$	Secondary supply voltage	-0.5 to 4.6	V
$V_D$	SubLVDS data bus input voltage (D+, D-)	-0.5 to 4.6	V
$V_{CLK}$	SubLVDS clock bus input voltage (CLK+, CLK-)	-0.5 to 4.6	V
$V_I$	DC input voltage (SYNC_SEL, EN)	-0.5 to 4.6	V
$V_O$	DC output voltage (D1-D8, H-SYNC, V-SYNC, CLK, I/O <sub>VDD</sub> )	-0.5 to ( $V_{DD} + 0.5$ )	V
$V_{I/OVL}$	DC output voltage (I/O <sub>VL</sub> )	-0.5 to ( $V_L + 0.5$ )	V
$T_{STG}$	Storage temperature range	-65 to +150	°C
ESD	Electrostatic discharge protection HBM Human body model (all pins)	±2	kV

*Note:* Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied.

**Table 5. Recommended operating conditions**

Symbol	Parameter	Min.	Typ.	Max.	Unit
$V_{DD}$	Main supply voltage	2.65	2.8	3.6	V
$V_L$	Secondary supply voltage	1.65	1.8	1.95	V
$V_{ID}$	Differential level input voltage (D+, D-, CLK1+, CLK1-)	0.1		0.4	V
$V_{CM}$	Common level input voltage (D+, D-, CLK1+, CLK1-)	0.5	0.9	1.3	V
$V_{IC}$	Level input voltage (SYNC_SEL, EN)			3.6	V
$V_{I/OVDD}$	Level input voltage (I/O <sub>VDD</sub> )			$V_{DD}$	V
$V_{I/OVL}$	Level input voltage (I/O <sub>VL</sub> )			$V_L$	V
$R_T$	Termination resistance (per pair differential input line)	80	100	120	Ω
$C_L$	Termination capacitance (per line vs gnd pin)		10		pF
$T_A$	Operating ambient temperature range	-40		85	°C
$T_J$	Operating junction temperature range	-40		125	°C
$t_R, t_F$	Rise and fall time (I/O <sub>VDD</sub> , I/O <sub>VL</sub> ; 10% to 90%; 90% to 10%)			600	ns

## 4 Electrical characteristics

**Table 6. Electrical characteristics** (Over recommended operating conditions unless otherwise noted. All typical values are at  $T_A = 25^\circ\text{C}$ , and  $V_{DD} = 2.8\text{V}$ ,  $V_L = 1.8\text{V}$ )

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{CM}$	Common mode input voltage (see fig.1)	$R_T = 100\Omega \pm 1\%$	0.5	0.9	1.3	V
$I_I$	Input leakage current (D+, D-, CLK1+, CLK1-)	$V_I = 0.4\text{V}$			$\pm 10$	$\mu\text{A}$
		$V_I = 1.4\text{V}$			$\pm 10$	$\mu\text{A}$
$I_S$	Supply current ( $I_L + I_{DD}$ )	EN= $V_{DD}$ , I/O $V_L = V_L$ , I/O $V_{DD} = V_{DD}$ , D+, CLK+ = Gnd or $V_{DD}$ , D+, CLK+ = $V_{DD}$ or Gnd		3.6	7.0	mA
$I_{SOFF}$	Shutdown supply current ( $I_L + I_{DD}$ )	EN=Gnd, $V_{DD}=2.65\text{V}$ to $3.6\text{V}$ $V_L=1.65\text{V}$ to $1.95\text{V}$			10	$\mu\text{A}$
$V_{IH}$	HIGH Level input voltage (SYNC_SEL, EN)	$V_{DD} = 2.65\text{V}$ to $3.6\text{V}$ $V_L = 1.65\text{V}$ to $1.95\text{V}$	$0.7 \times V_{DD}$		3.6	V
$V_{IL}$	LOW Level input voltage (SYNC_SEL, EN)	$V_{DD} = 2.65\text{V}$ to $3.6\text{V}$ $V_L = 1.65\text{V}$ to $1.95\text{V}$	0		$0.3 \times V_{DD}$	V
$I_{IH}$	HIGH Level input current (SYNC_SEL, EN)	$V_{IH} = 0.7 \times V_{DD}$			$\pm 10$	$\mu\text{A}$
$I_{IL}$	LOW Level input current (SYNC_SEL, EN)	$V_{IL} = 0.3 \times V_{DD}$			$\pm 10$	$\mu\text{A}$
$V_{OH}$	HIGH Level output voltage (D1-D8, H-SYNC, V-SYNC, CLK)	$I_{OH} = -8\text{mA}$	2.0			V
		$I_{OH} = -4\text{mA}$	2.4			V
$V_{OL}$	LOW Level output voltage (D1-D8, H-SYNC, V-SYNC, CLK)	$I_{OL} = +8\text{mA}$			0.60	V
$V_{IH2}$	HIGH Level input voltage (I/O $V_{L1}$ , I/O $V_{L2}$ )	$V_{DD} = 2.65\text{V}$ to $3.6\text{V}$ $V_L = 1.65\text{V}$ to $1.95\text{V}$	$0.7 \times V_L$			V
		$V_{DD} = 2.65\text{V}$ to $3.6\text{V}$ $V_L = 1.65\text{V}$ to $1.95\text{V}$	$0.7 \times V_{DD}$			V
$V_{IL2}$	LOW Level input voltage (I/O $V_{L1}$ , I/O $V_{L2}$ )	$V_{DD} = 2.65\text{V}$ to $3.6\text{V}$ $V_L = 1.65\text{V}$ to $1.95\text{V}$	0		0.25	V
		$V_{DD} = 2.65\text{V}$ to $3.6\text{V}$ $V_L = 1.65\text{V}$ to $1.95\text{V}$	0		0.25	V
$V_{OH2}$	HIGH Level output voltage (I/O $V_{L1}$ , I/O $V_{L2}$ )	$I_{OH} = -20\mu\text{A}$ $V_{I/OVDD} = V_{DD}$	$V_L - 0.4$			V
		$I_{OH} = -20\mu\text{A}$ $V_{I/OVL} = V_L$	$V_{DD} - 0.4$			V
$V_{OL2}$	LOW Level output voltage (I/O $V_{L1}$ , I/O $V_{L2}$ , I/O $V_{DD1}$ , I/O $V_{DD2}$ )	$I_{OL} = +1\text{mA}$ , $V_{I/OVL}$ or $V_{I/OVDD} = \text{Gnd}$			0.35	V



**Table 7. Switching characteristics** ( $R_T = 100\Omega \pm 1\%$ ,  $C_L = 10\text{pF}$ , over recommended operating conditions unless otherwise noted. Typical values are referred to  $T_A = 25^\circ\text{C}$  and  $V_{DD} = 2.8\text{V}$ ,  $V_L = 1.8\text{V}$ )

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_r$	Rise time LVTTTL Output voltage (10% to 90%)			3.1	4.0	ns
$t_f$	Fall time LVTTTL output voltage (90% to 10%)			2.0	4.0	ns
$t_{r\ I/O}$	Rise time I <sup>2</sup> C input/output voltage (20% to 80%)				320	ns
$t_{f\ I/O}$	Fall time I <sup>2</sup> C input/output voltage (80% to 20%)				20	ns
$t_{pLH}$	Propagation delay time (CLK to V-SYNC, H-SYNC) (low to high)			6.5	8.5	ns
$t_{pHL}$	Propagation delay time (CLK to V-SYNC, H-SYNC) (high to low)			6.5	8.5	ns
$t_{pLH}$	Propagation delay time (CLK to D1-D8) (low to high)			6.5	8.5	ns
$t_{pHL}$	Propagation delay time (CLK to D1-D8) (high to low)			6.5	8.5	ns
$t_{pLH}$	Propagation delay time I <sup>2</sup> C input/output voltage (50% to 50%) (Low to High)				100	ns
$t_{pHL}$	Propagation delay time I <sup>2</sup> C input/output voltage (50% to 50%) (High to Low)				10	ns
$t_{EN}$	Enable delay time (EN to V-SYNC, H-SYNC: $t_{pZL}$ , $t_{pZH}$ )	$t_{rEN} = 2.0\text{ns}$ (10% to 90%) $t_{fEN} = 2.0\text{ns}$ (90% to 10%)			20	$\mu\text{s}$
$t_{DIS}$	Disable delay time (EN to V-SYNC, H-SYNC: $t_{pLZ}$ , $t_{pHZ}$ )	$t_{rEN} = 2.0\text{ns}$ (10% to 90%) $t_{fEN} = 2.0\text{ns}$ (90% to 10%)			1000	ns
$f_{OPR}$	Operating frequency	$t_{rD,CLK} = 400\text{ps}$ (10% to 90%) $t_{fD,CLK} = 400\text{ps}$ (90% to 10%) $V_{CM\ D,CLK} = 0.9\text{V}$ , $V_{DD,CLK} = 150\text{mV}$	1		416	MHz
$T_{CLK}$	Clock Period		2.4		1000	ns
$t_{SUD-CLK}$	Setup time (D to CLK) (low to high or high to low vs positive CLK edge) (note 1) (see fig. 6)		0.6			ns
$t_{HCLK-D}$	Hold time (CLK to D) (positive CLK edge to D) (note 1) (see fig. 6)		1.0			ns

Note: 1 50%  $V_{DIN}$  to 50%  $V_{DOUT}$

**Table 8. Capacitive characteristics**

Symbol	Parameter	Test condition		Value			Unit
		$V_{DD}$ (V)		$T_A = 25^\circ\text{C}$			
				Min.	Typ.	Max.	
$C_{IN}$	Input Capacitance (SYNC_SEL, EN)	2.65 to 3.6	$V_L = 1.65\text{V}$ to $1.95\text{V}$ , $V_I = \text{GND}$ or $V_{DD}$		3.5		pF

# 5 Timing diagram

(unless otherwise specified  $T_A = 25^\circ\text{C}$ )

Figure 6.  $t_{\text{SUD-CLK}}$ ,  $t_{\text{HCLK-D}}$  (Differential input signals D+,D- and CLK+,CLK-)

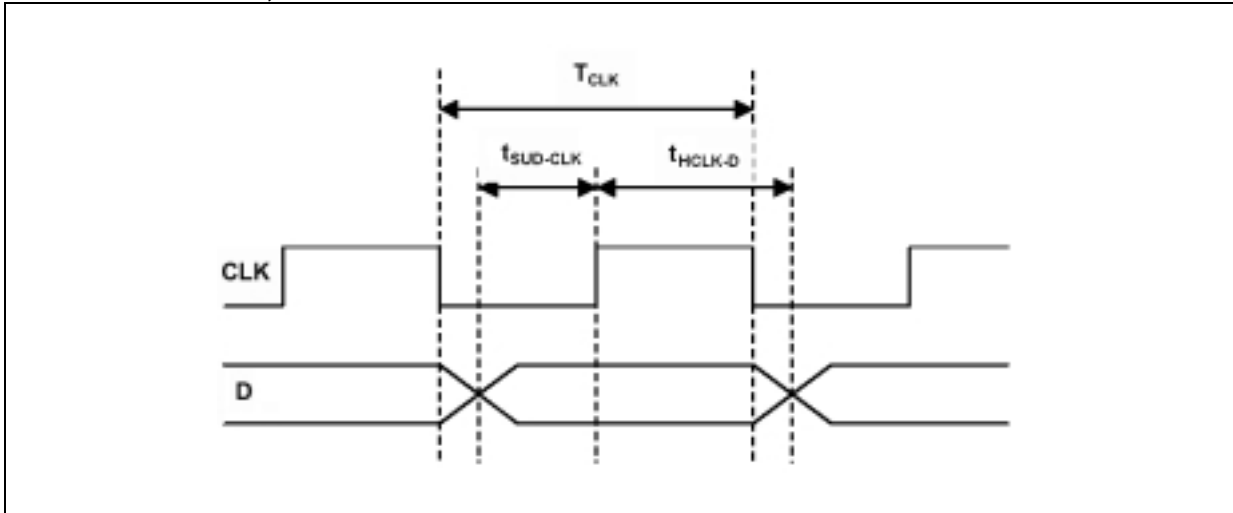
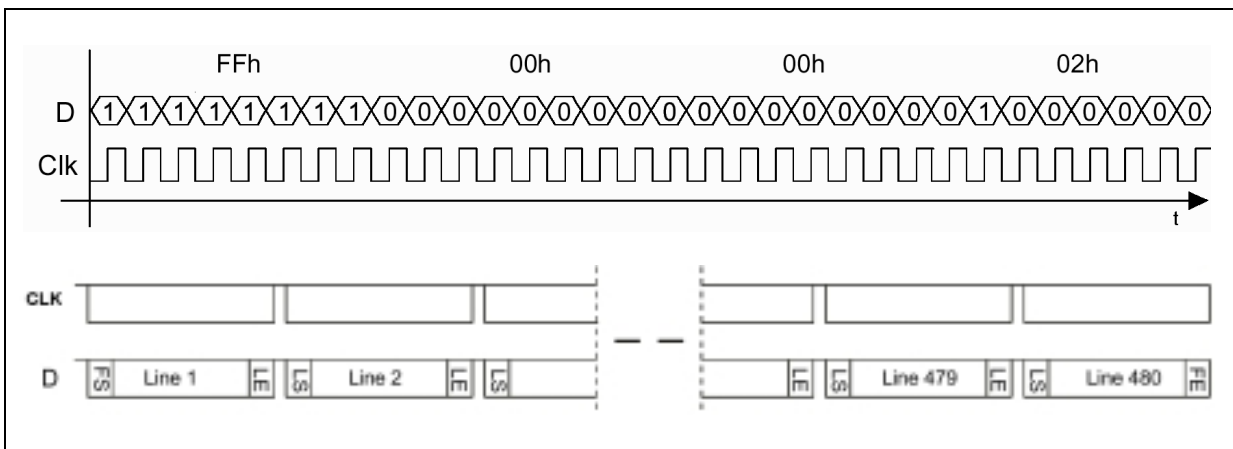
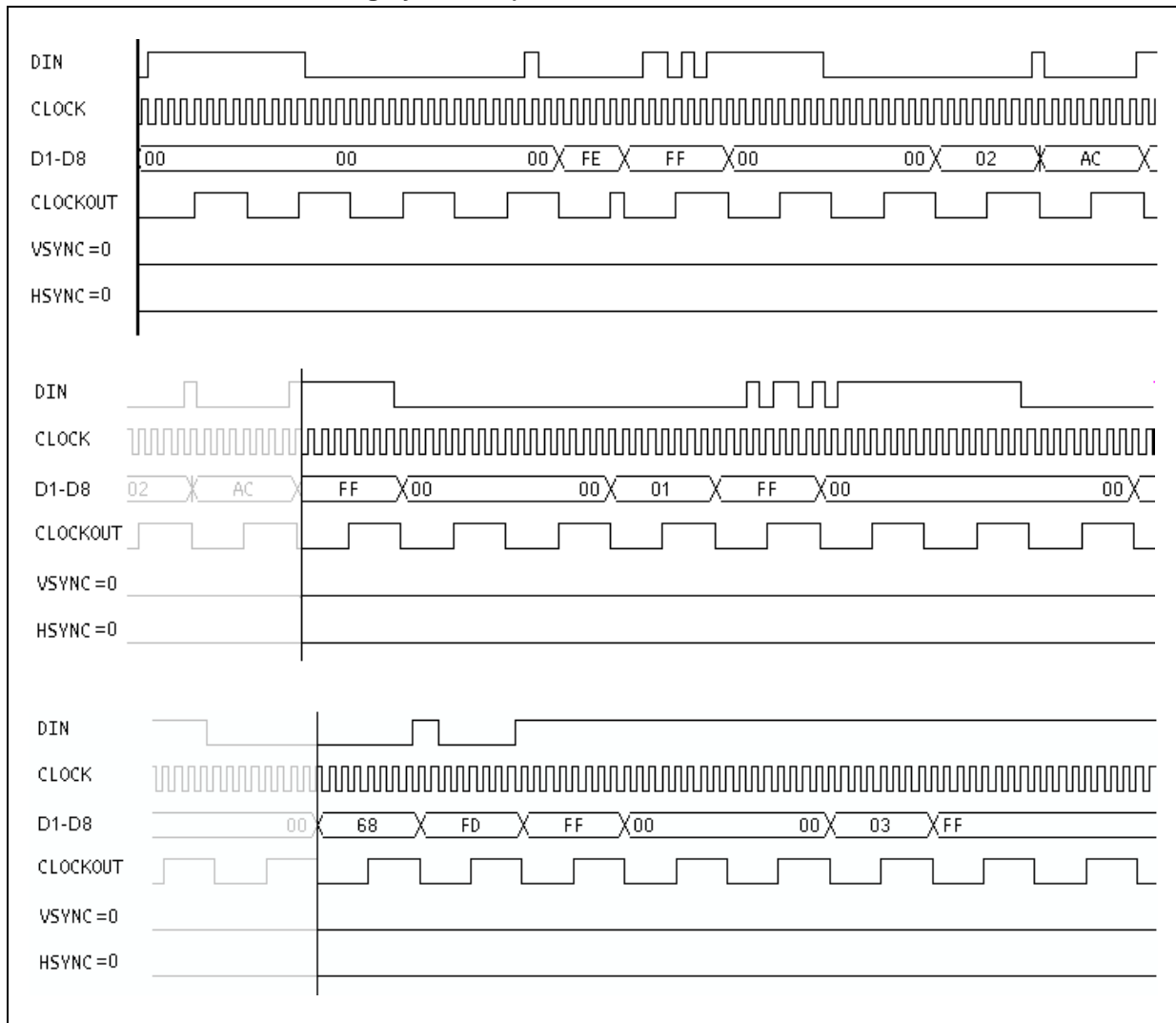


Figure 7. Bit order in synchronization codes and data, LSB first (example start of frame), image frame structure



Note: *LSB (byte-wise Least Significant Bit first)*

**Figure 8. Disabled sync mode free running clock IN (SYNC\_SEL=GND) (D1-D8 will get out input data DIN, including sync code)**



**Figure 9. Enabled sync mode free running clock IN (SYNC\_SEL=V<sub>DD</sub>) (D1-D8 will get out input data DIN only, excluding sync code)**

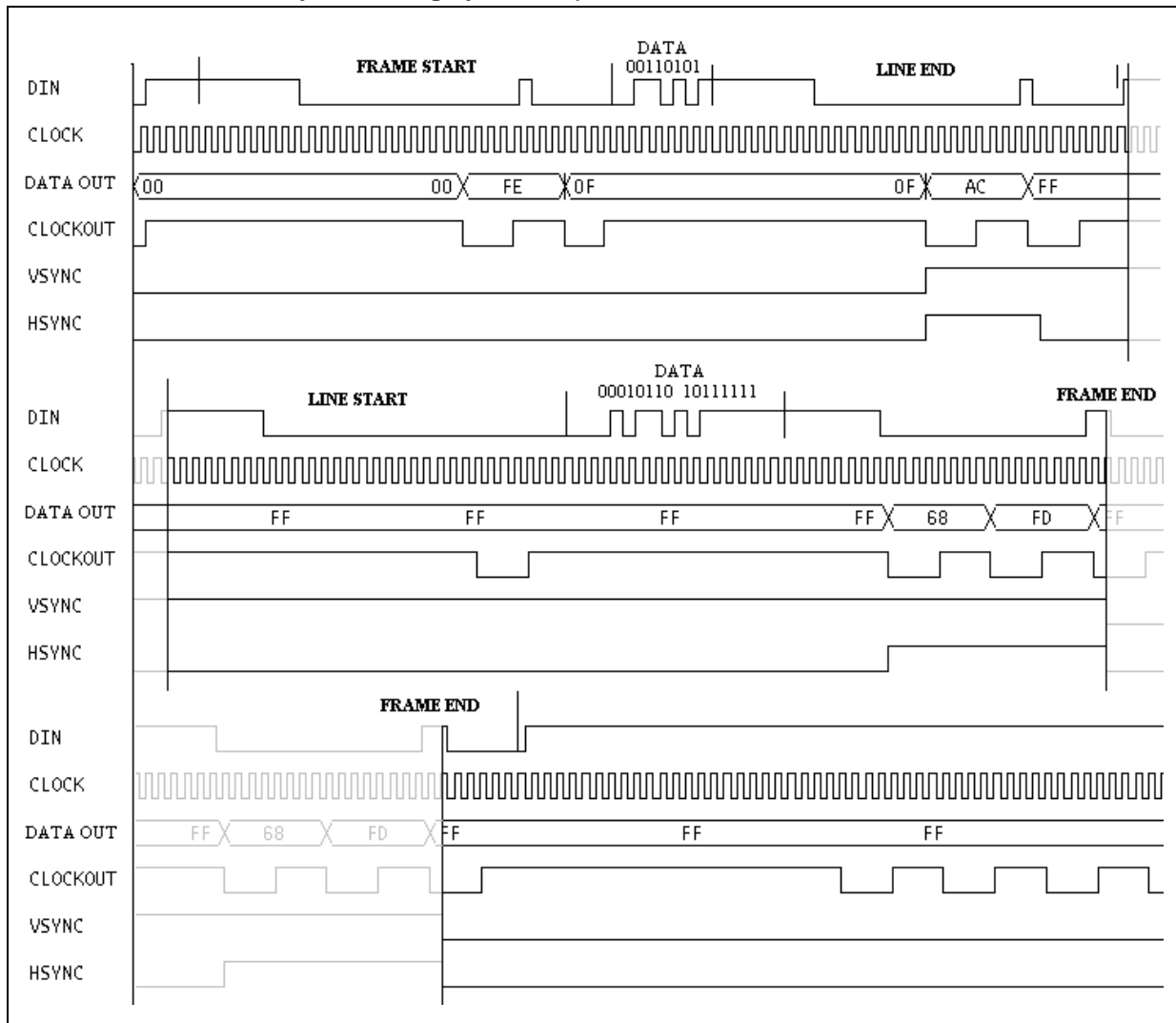
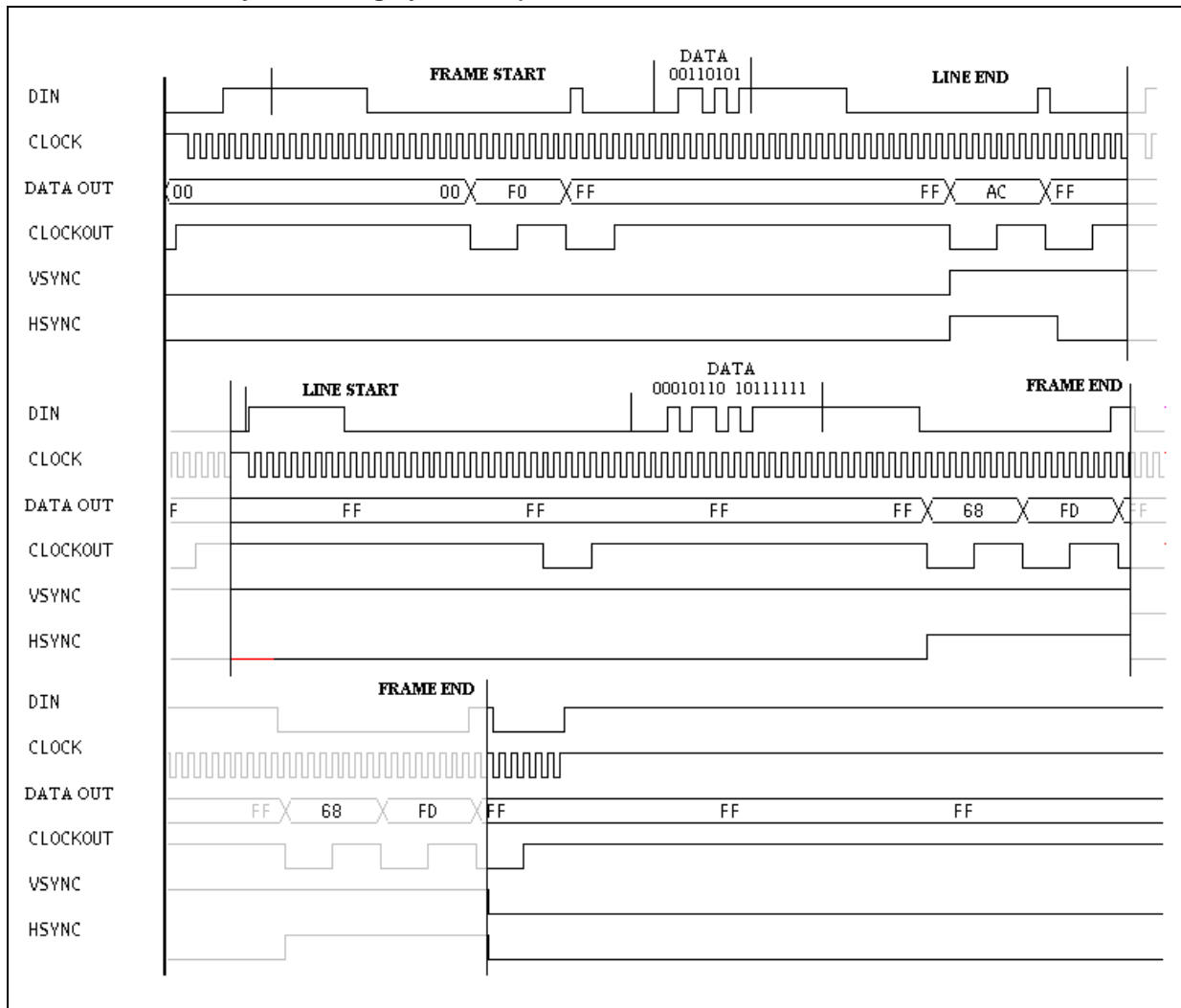
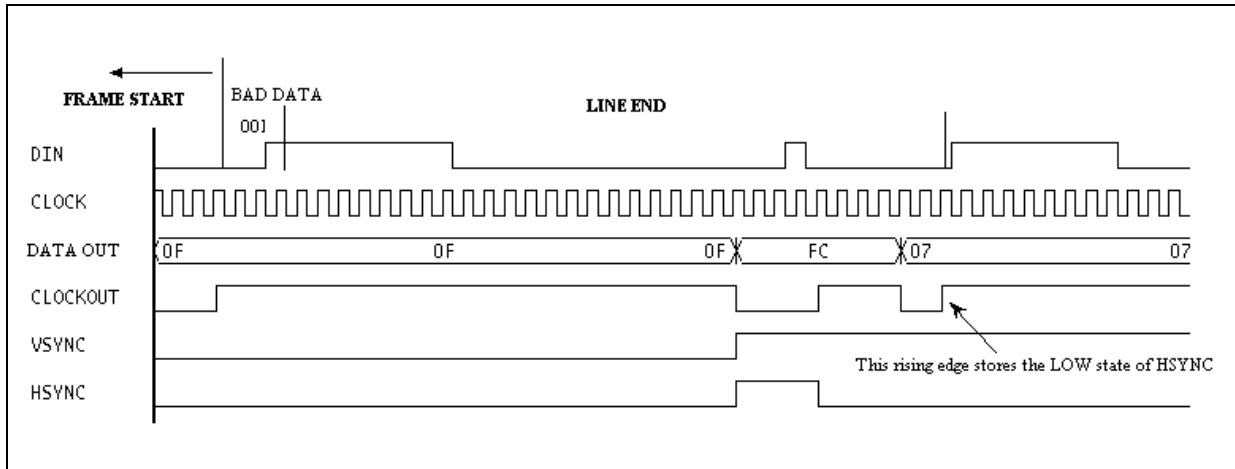


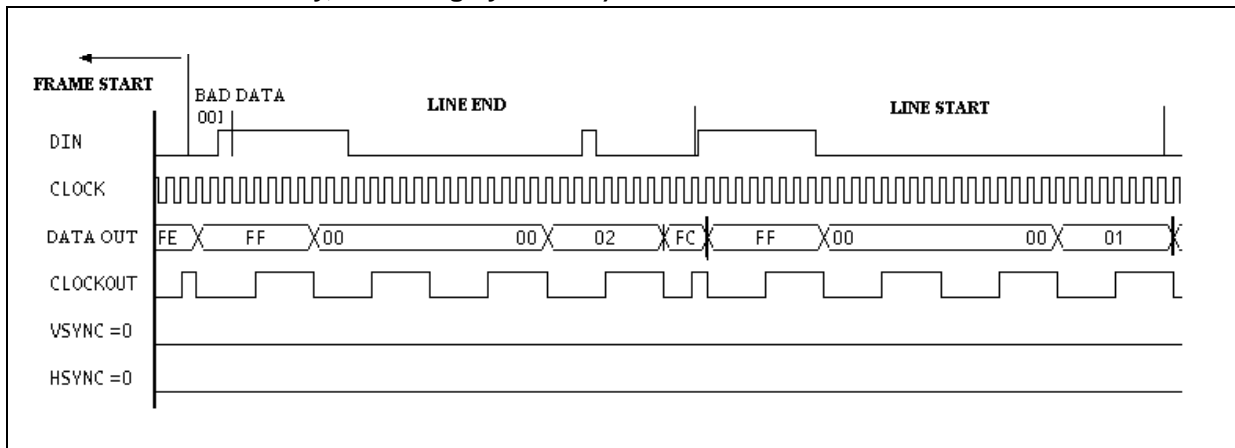
Figure 10. Enabled sync mode gated clock IN (SYNC\_SEL=VDD) (D1-D8 will get out input data DIN only, excluding sync code)



**Figure 11. Enabled sync mode free running clock IN (SYNC\_SEL=V<sub>DD</sub>) (D1-D8 will get out input data DIN only, excluding sync code)**



**Figure 12. Disabled sync mode free running clock IN (SYNC\_SEL=Gnd) (D1-D8 will get out input data DIN only, excluding sync code)**

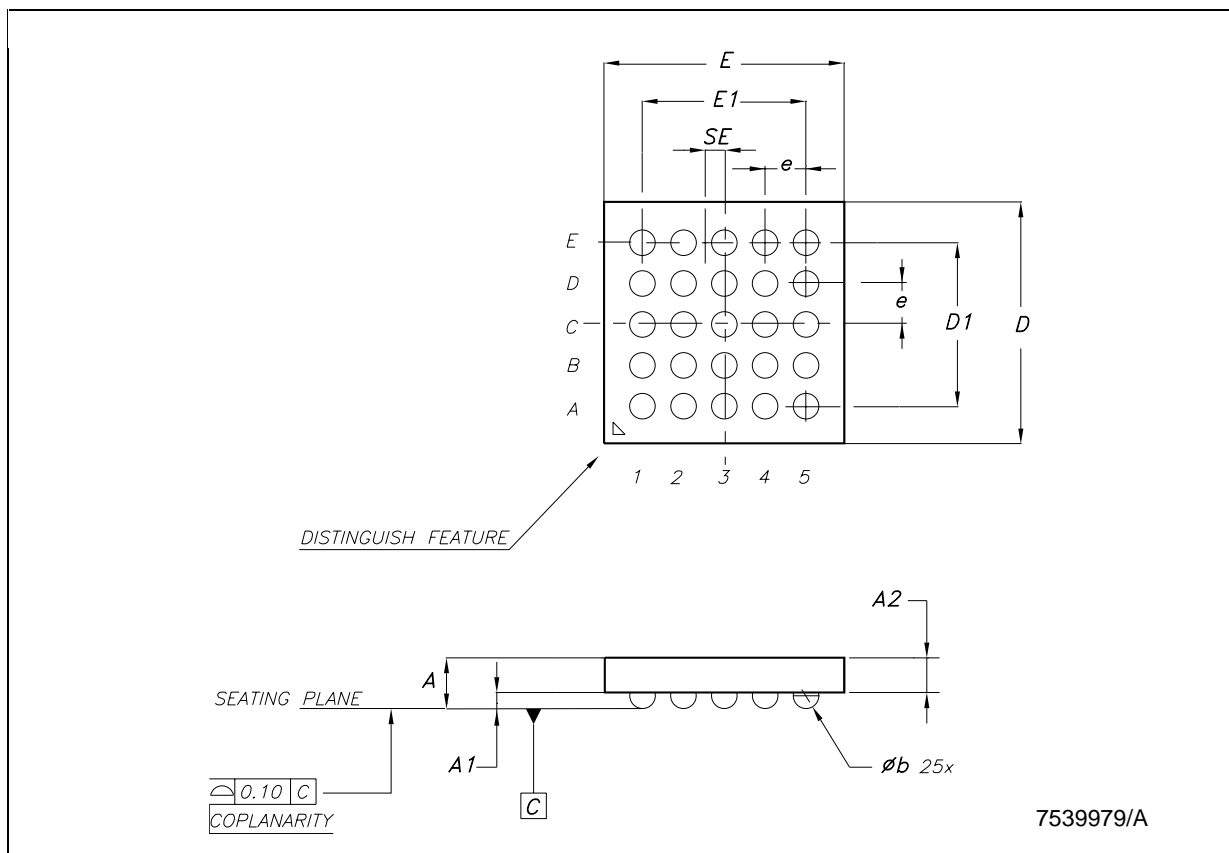


## 6 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com).

**μTFBGA25 MECHANICAL DATA**

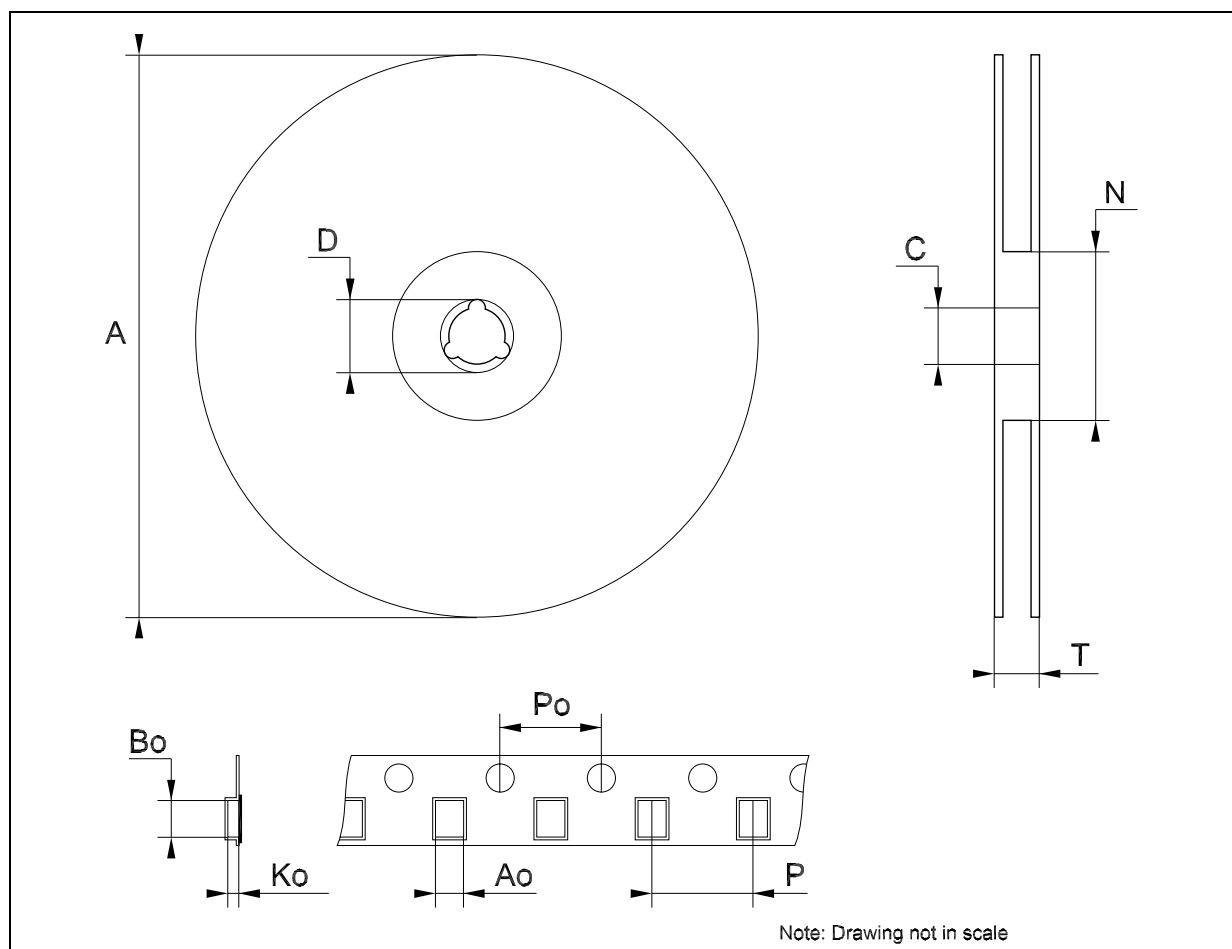
DIM.	mm.			mils		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	1.0	1.1	1.16	39.4	43.3	45.7
A1			0.25			9.8
A2	0.78		0.86	30.7		33.9
b	0.25	0.30	0.35	9.8	11.8	13.8
D	2.9	3.0	3.1	114.2	118.1	122.0
D1		2			78.8	
E	2.9	3.0	3.1	114.2	118.1	122.0
E1		2			78.8	
e		0.5			19.7	
SE		0.25			9.8	





### Tape & Reel TFBGA25 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			14.4			0.567
Ao		3.3			0.130	
Bo		3.3			0.130	
Ko		1.60			0.063	
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319



## 7 Revision history

**Table 9. Revision history**

Date	Revision	Changes
12-Apr-2006	1	Initial release.

**Please Read Carefully:**

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

**UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.**

**UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED REPRESENTATIVE OF ST, ST PRODUCTS ARE NOT DESIGNED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS, WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE.**

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2006 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)